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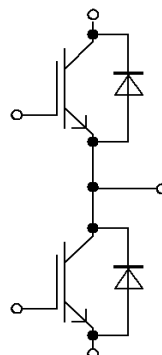
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62mm C-Serien Modul mit Trench/Feldstopp IGBT4 und Emitter Controlled 3 Diode
62mm C-Series module with Trench/Fieldstop IGBT4 and Emitter Controlled 3 diode

Vorläufige Daten / Preliminary Data



$V_{CES} = 1700V$
 $I_{C\ nom} = 500A / I_{CRM} = 1000A$

Typische Anwendungen

- Hochleistungsumrichter
- Motorantriebe
- USV-Systeme
- Windgeneratoren

Typical Applications

- High power converters
- Motor drives
- UPS systems
- Wind turbines

Elektrische Eigenschaften

- Erweiterte Sperrschichttemperatur $T_{vj\ op}$
- Niedriges V_{CEsat}
- Sehr große Robustheit
- V_{CEsat} mit positivem Temperaturkoeffizienten

Electrical Features

- Extended operating temperature $T_{vj\ op}$
- Low V_{CEsat}
- Unbeatable robustness
- V_{CEsat} with positive temperature coefficient

Mechanische Eigenschaften

- 4 kV AC 1min Isolationsfestigkeit
- Gehäuse mit CTI > 400
- Große Luft- und Kriechstrecken
- Isolierte Bodenplatte
- Standardgehäuse

Mechanical Features

- 4 kV AC 1min insulation
- Package with CTI > 400
- High creepage and clearance distances
- Isolated base plate
- Standard housing

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

| | Digit |
|----------------------------|--------------|
| Module Serial Number | 1 - 5 |
| Module Material Number | 6 - 11 |
| Production Order Number | 12 - 19 |
| Datecode (Production Year) | 20 - 21 |
| Datecode (Production Week) | 22 - 23 |

| | | |
|-----------------|---------------------------------|----------------------|
| prepared by: CE | date of publication: 2016-08-09 | |
| approved by: MK | revision: V2.0 | UL approved (E83335) |

**Vorläufige Daten
Preliminary Data**

**IGBT, Wechselrichter / IGBT, Inverter
Höchstzulässige Werte / Maximum Rated Values**

| | | | | |
|--|---|-------------------|-------|---|
| Kollektor-Emitter-Sperrspannung Collector-emitter voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{CES} | 1700 | V |
| Kollektor-Dauergleichstrom Continuous DC collector current | $T_C = 100^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$ | $I_{C\text{nom}}$ | 500 | A |
| Periodischer Kollektor-Spitzenstrom Repetitive peak collector current | $t_P = 1\text{ ms}$ | I_{CRM} | 1000 | A |
| Gate-Emitter-Spitzenspannung Gate-emitter peak voltage | | V_{GES} | +/-20 | V |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | | |
|---|---|---|--------------------|----------------------|------|-------------|---|
| Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage | $I_C = 500\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 500\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 500\text{ A}, V_{GE} = 15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | $V_{CE\text{sat}}$ | 1,95 2,35 2,45 | 2,30 | V V V | |
| Gate-Schwellenspannung Gate threshold voltage | $I_C = 20,0\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$ | | V_{GEth} | 5,20 | 5,80 | 6,40 | V |
| Gateladung Gate charge | $V_{GE} = -15\text{ V} \dots +15\text{ V}$ | | Q_G | 5,75 | | | μC |
| Interner Gatewiderstand Internal gate resistor | $T_{vj} = 25^{\circ}\text{C}$ | | R_{Gint} | 1,3 | | | Ω |
| Eingangskapazität Input capacitance | $f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{ies} | 45,0 | | | nF |
| Rückwirkungskapazität Reverse transfer capacitance | $f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{res} | 1,45 | | | nF |
| Kollektor-Emitter-Reststrom Collector-emitter cut-off current | $V_{CE} = 1700\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{CES} | | | 1,0 | mA |
| Gate-Emitter-Reststrom Gate-emitter leakage current | $V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{GES} | | | 400 | nA |
| Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load | $I_C = 500\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | t_{don} | 0,22 0,25 0,26 | | | μs μs μs |
| Anstiegszeit, induktive Last Rise time, inductive load | $I_C = 500\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | t_r | 0,04 0,05 0,05 | | | μs μs μs |
| Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load | $I_C = 500\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | t_{doff} | 0,53 0,67 0,71 | | | μs μs μs |
| Fallzeit, induktive Last Fall time, inductive load | $I_C = 500\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | t_f | 0,10 0,16 0,18 | | | μs μs μs |
| Einschaltverlustenergie pro Puls Turn-on energy loss per pulse | $I_C = 500\text{ A}, V_{CE} = 900\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 10000\text{ A}/\mu\text{s}$ ($T_{vj} = 150^{\circ}\text{C}$) $R_{Gon} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | E_{on} | 91,5 130 140 | | | mJ mJ mJ |
| Abschaltverlustenergie pro Puls Turn-off energy loss per pulse | $I_C = 500\text{ A}, V_{CE} = 900\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3000\text{ V}/\mu\text{s}$ ($T_{vj} = 150^{\circ}\text{C}$) $R_{Goff} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | E_{off} | 94,0 155 170 | | | mJ mJ mJ |
| Kurzschlußverhalten SC data | $V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CE\max} = V_{CES} - L_{sCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$ | | I_{SC} | 2000 | | | A |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro IGBT / per IGBT | | R_{thJC} | | | 0,0485 | K/W |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro IGBT / per IGBT $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | | | 0,0241 | K/W |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj\text{op}}$ | -40 | | 150 | $^{\circ}\text{C}$ |

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**Vorläufige Daten
Preliminary Data**

Diode, Wechselrichter / Diode, Inverter

Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|---|--|-----------|----------------|--|
| Periodische Spitzensperrspannung Repetitive peak reverse voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{RRM} | 1700 | V |
| Dauergleichstrom Continuous DC forward current | | I_F | 500 | A |
| Periodischer Spitzenstrom Repetitive peak forward current | $t_P = 1 \text{ ms}$ | I_{FRM} | 1000 | A |
| Grenzlastintegral I^2t - value | $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$ | I^2t | 33000 31500 | A^2s A^2s |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|---|---|-------------|----------------------|-------|---|
| Durchlassspannung Forward voltage | $I_F = 500 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 500 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 500 \text{ A}, V_{GE} = 0 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | V_F | 1,95 2,10 2,15 | 2,60 | V V V |
| Rückstromspitze Peak reverse recovery current | $I_F = 500 \text{ A}, -di_F/dt = 10000 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | I_{RM} | 770 815 825 | | A A A |
| Sperrverzögerungsladung Recovered charge | $I_F = 500 \text{ A}, -di_F/dt = 10000 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | Q_r | 120 195 215 | | μC μC μC |
| Abschaltenergie pro Puls Reverse recovery energy | $I_F = 500 \text{ A}, -di_F/dt = 10000 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | E_{rec} | 69,0 120 135 | | mJ mJ mJ |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro Diode / per diode | | R_{thJC} | | 0,104 | K/W |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro Diode / per diode $\lambda_{Paste} = 1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | 0,0354 | | K/W |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj op}$ | -40 | 150 | $^{\circ}\text{C}$ |

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**Vorläufige Daten
Preliminary Data**

Modul / Module

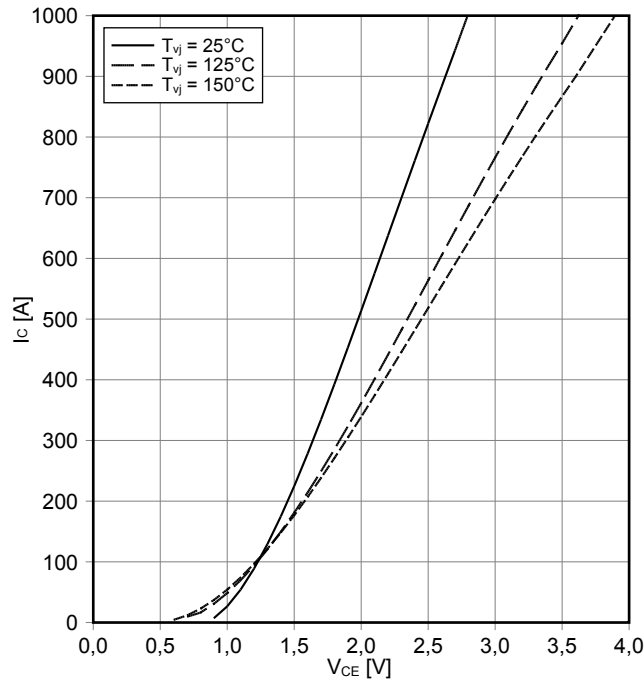
| | | | | | |
|---|--|----------------------|--------------------------------|------|---------|
| Isolations-Prüfspannung Isolation test voltage | RMS, f = 50 Hz, t = 1 min. | V _{ISOL} | 4,0 | | kV |
| Material Modulgrundplatte Material of module baseplate | | | Cu | | |
| Innere Isolation Internal isolation | Basisisolation (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140) | | Al ₂ O ₃ | | |
| Kriechstrecke Creepage distance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 29,0 23,0 | | mm |
| Luftstrecke Clearance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 23,0 11,0 | | mm |
| Vergleichszahl der Kriechwegbildung Comperative tracking index | | CTI | > 400 | | |
| | | | min. typ. max. | | |
| Modulstreuintuktivität Stray inductance module | | L _{sCE} | | 20 | nH |
| Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip | T _C = 25°C, pro Schalter / per switch | R _{CC'+EE'} | | 0,46 | mΩ |
| Lagertemperatur Storage temperature | | T _{stg} | -40 | | 125 °C |
| Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting | Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note | M | 3,00 | | 6,00 Nm |
| Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque | Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note | M | 2,5 | - | 5,0 Nm |
| Gewicht Weight | | G | | 340 | g |

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Preliminary Data**

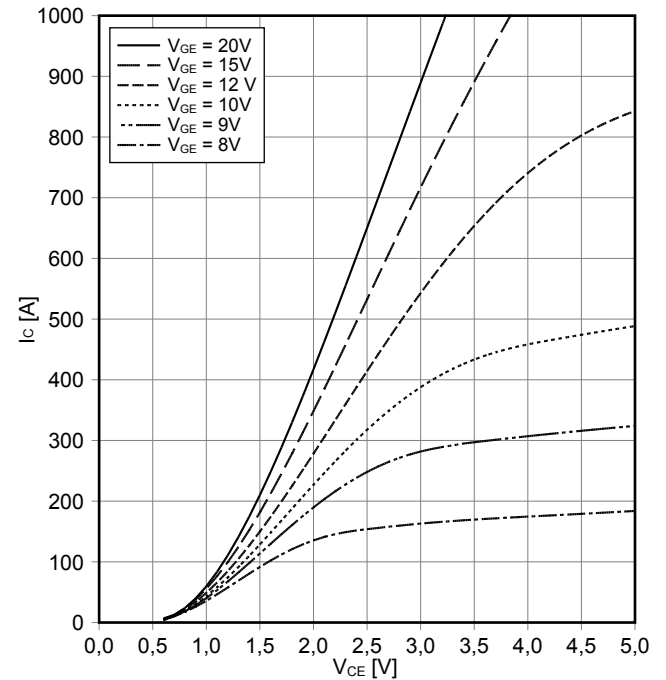
**Ausgangskennlinie IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)**

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



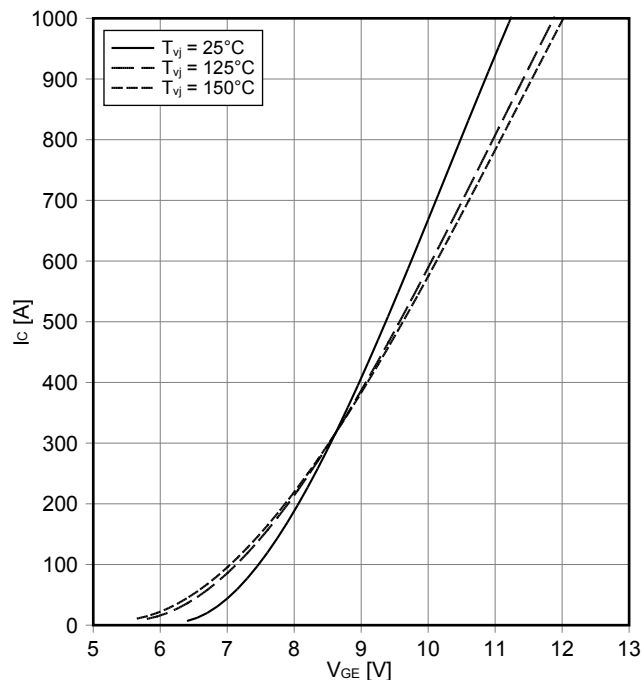
**Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)**

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



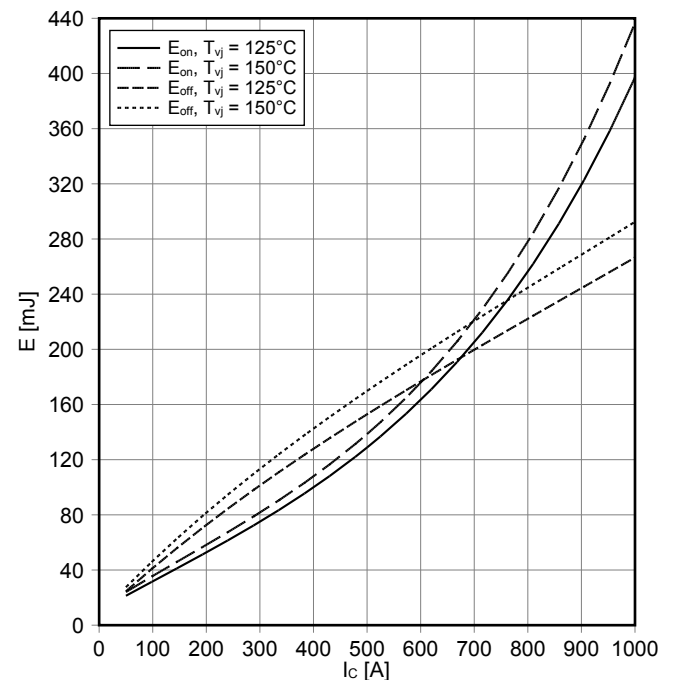
**Übertragungscharakteristik IGBT, Wechselrichter (typisch)
transfer characteristic IGBT, Inverter (typical)**

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



**Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)**

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1\ \Omega$, $R_{Goff} = 1\ \Omega$, $V_{CE} = 900\text{ V}$

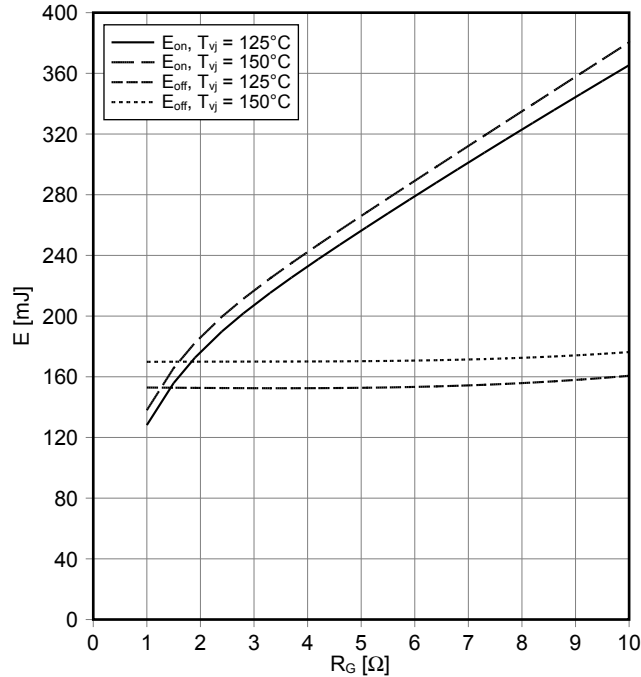


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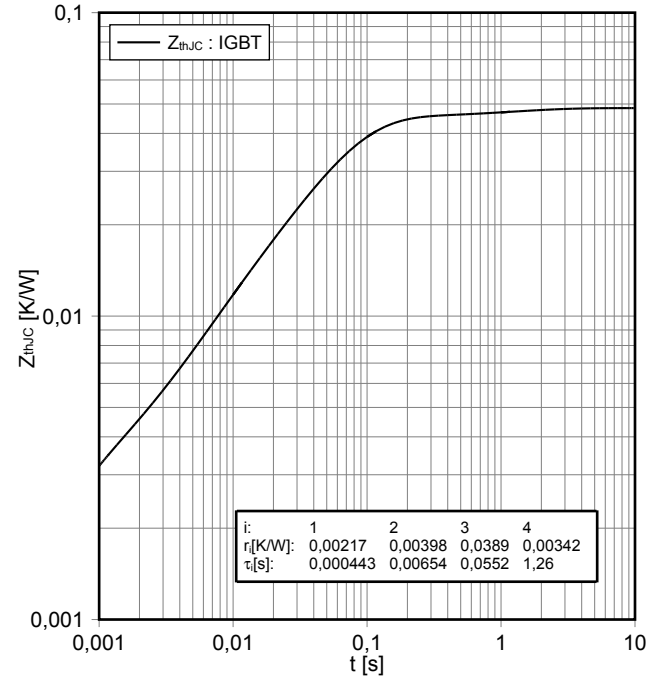
**Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)**

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 500\text{ A}$, $V_{CE} = 900\text{ V}$



**Transienter Wärmewiderstand IGBT, Wechselrichter
transient thermal impedance IGBT, Inverter**

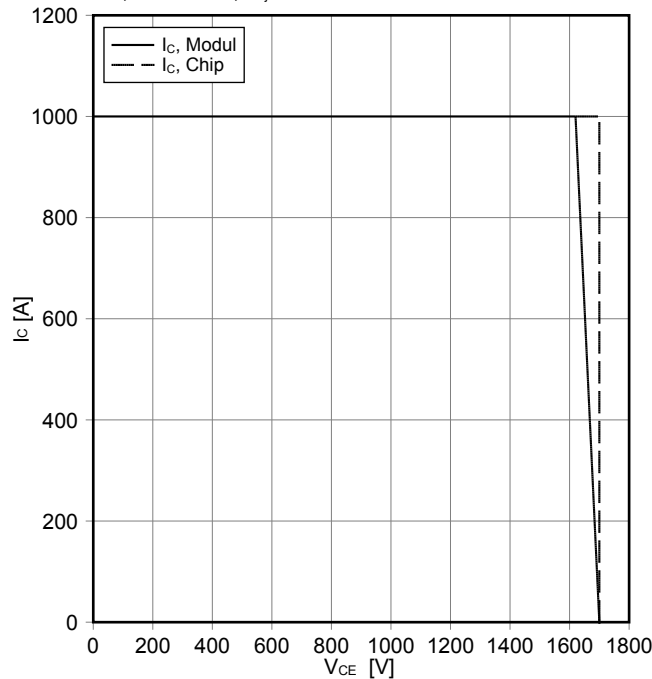
$Z_{thJC} = f(t)$



**Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter
(RBSOA)**

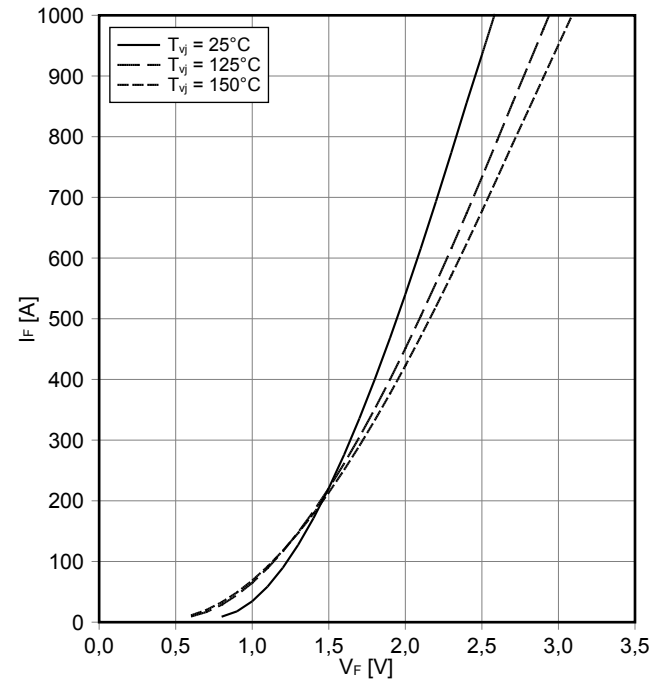
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 1\ \Omega$, $T_{vj} = 150^\circ\text{C}$



**Durchlasskennlinie der Diode, Wechselrichter (typisch)
forward characteristic of Diode, Inverter (typical)**

$I_F = f(V_F)$



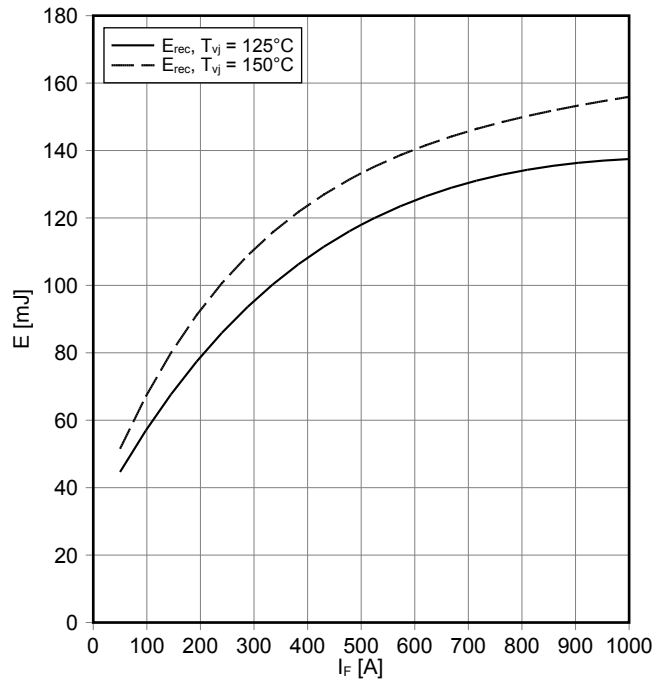
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Preliminary Data

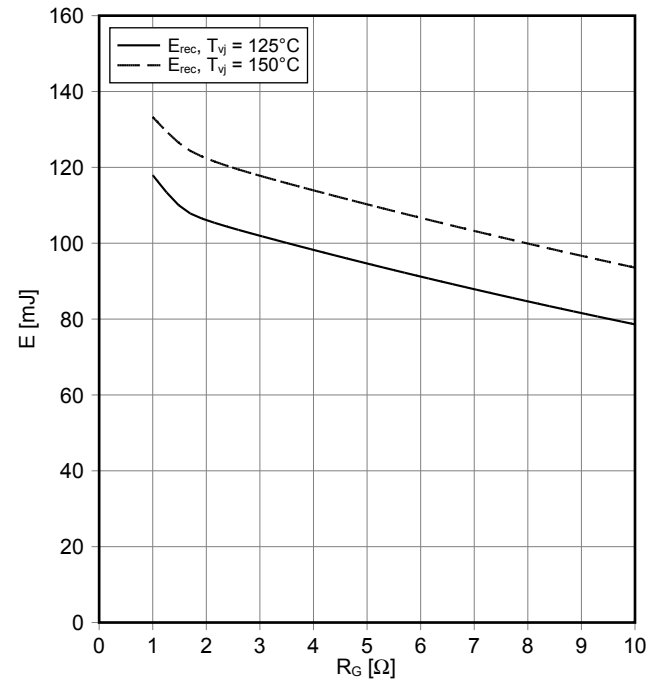
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 1 \Omega, V_{CE} = 900 V$



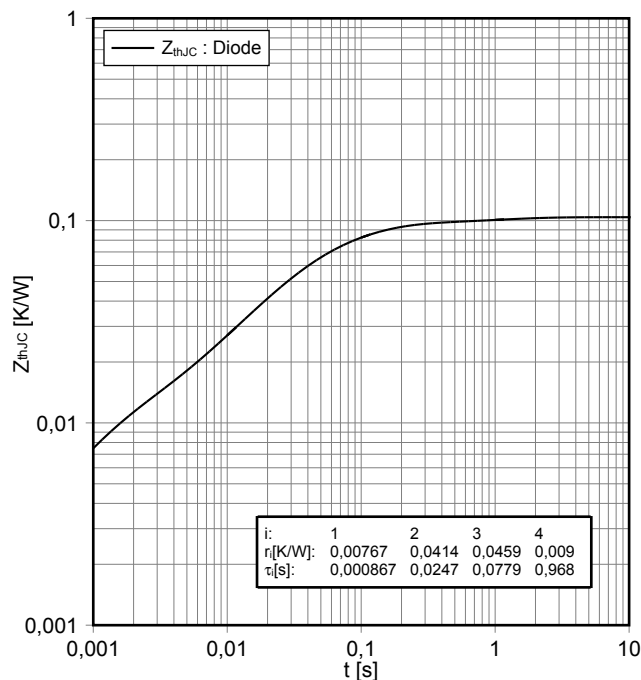
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 500 A, V_{CE} = 900 V$



Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter

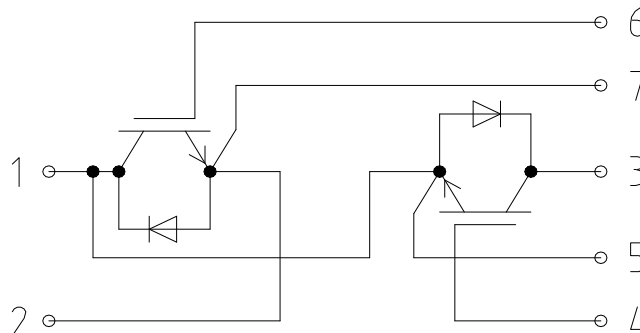
$Z_{thJC} = f(t)$



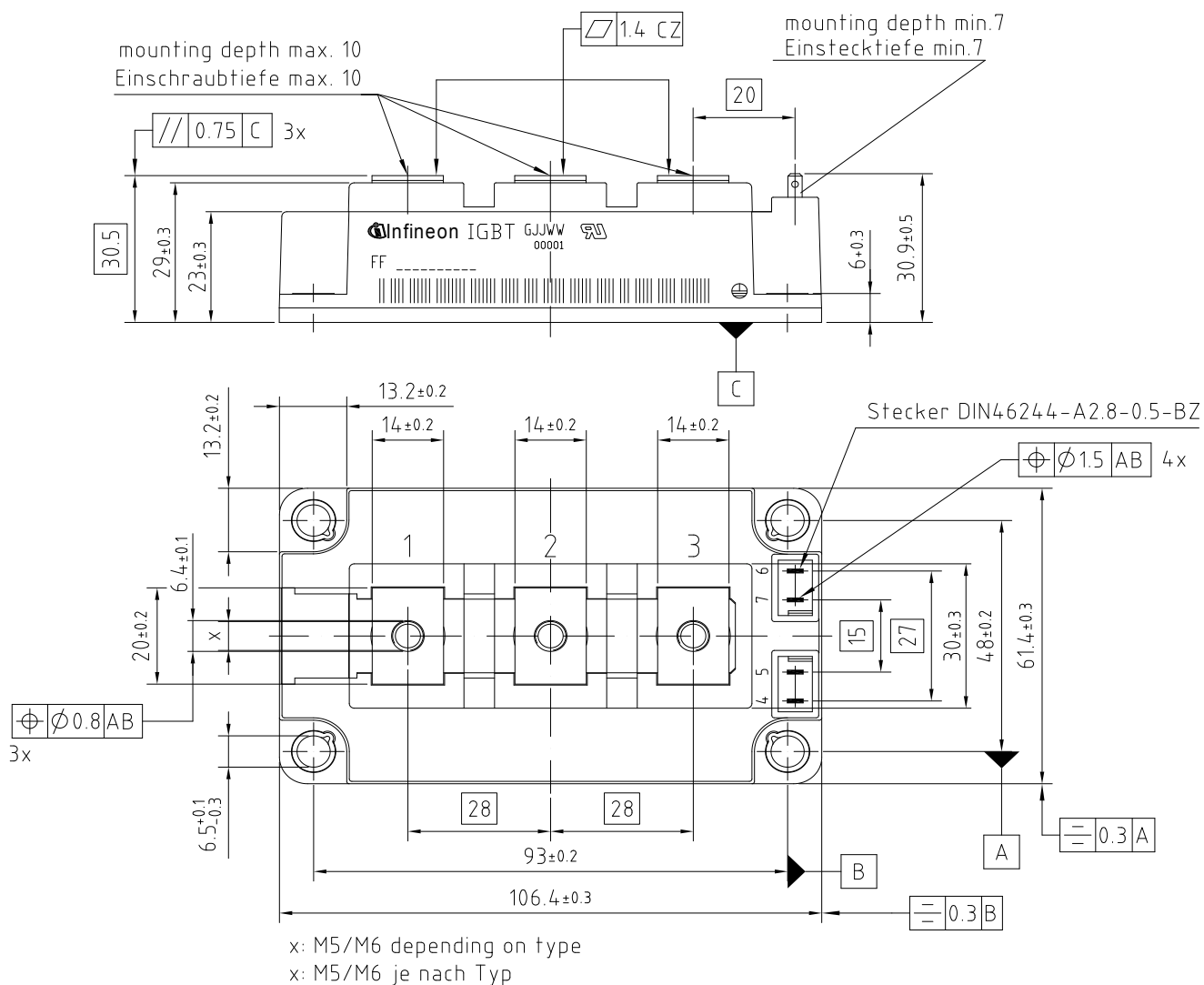
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Vorläufige Daten
Preliminary Data

Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



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**Vorläufige Daten
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